



Customer Information Notification

201705018I

Issue Date: 09-Jul-2017

Effective Date: 10-Jul-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

☐ Wafer Fab Process

☐ Assembly Process

☐ Product Marking

☐ Test Location

☐ Design

☐ Wafer Fab Materials

☒ Assembly Materials

☐ Mechanical Specification

☐ Test Process

☐ Errata

☐ Wafer Fab Location

☐ Assembly Location

☐ Packing/Shipping/Labeling Equipment

☐ Test

☐ Electrical spec./Test coverage

MPC5602D/P Kapton Tape Addition & Fiducial Plating Removal On Leadframe of 100LQFP

Information Notification

NXP Semiconductors will be implementing Kapton Tape application on the lead frame of 100LQFP package for MPC5602D and MPC5602P. In addition, NXP will be removing the redundant fiducial plating from the flag on the leadframe.

The only change to the device is the addition of Kapton Tape applied onto the lead frame and removal of the fiducial plating. There is no change to the trimmed dimension to the product.

No corresponding ZVEI Delta Qualification Matrix ID applicable for this change. Therefore, there is no Delta Qualification Matrix attached with this notification.

Why do we issue this Information Notification

The Kapton Tape applied onto the lead frame will be visible when the device is inspected under C-Mode Scanning Acoustic Microscopy (CSAM).

The application of this tape is a quality improvement which will reduce or eliminate lead frame inner lead bend occurrence.

Fiducial plating is redundant. Removal of fiducial plating to standardize to current leadframe design.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

SPC5602PEF0MLL6